

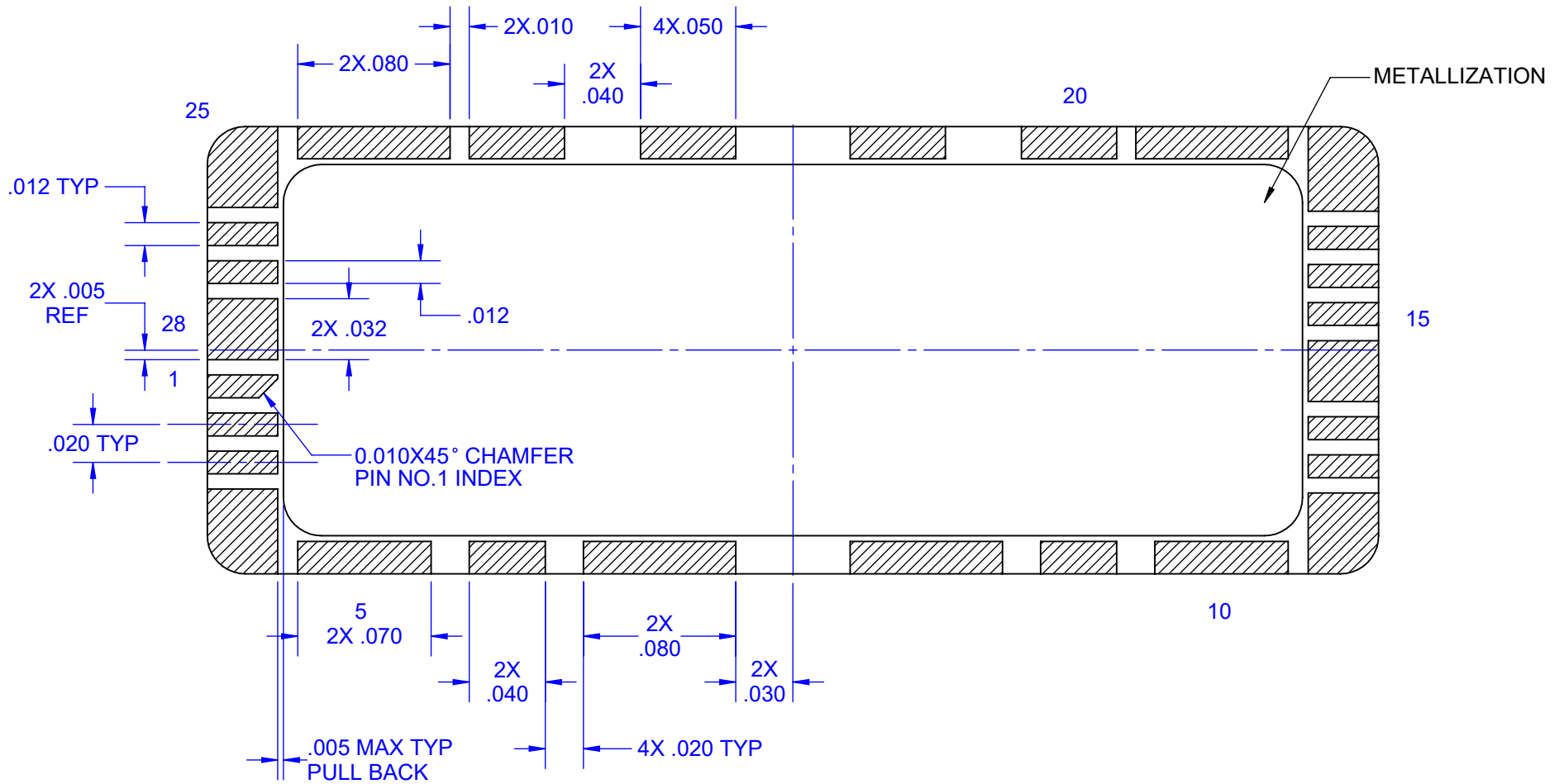
DETAIL B
SCALE 8 : 1

- NOTES:
1. GOLD PLATE 60 micro-inch over 100 micro-inch (MIN) NICKEL.
 2. SEAL AREA TO BE METALLIZED.
 3. SEE PART NUMBER TABLE FOR DIE ATTACH METALLIZATION.
 4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
 5. LEAD RESISTANCE: 0.35 OHM MAX.
 6. TOLERANCE ± 0.005 -INCH UNLESS OTHERWISE SPECIFIED.
 7. CERAMIC (Al_2O_3 BLACK) SIDE-BRAZE PACKAGE KOVAR LEAD FRAME WITH GOLD METALLIZATION.


PART NUMBER TABLE		
PART NUMBER	DIE PAD	DWG
CERDIP28F3-N195x535	GOLD	281953

APPROVALS	DATE	TopLine [®]			
DRAWN T. Au	4/14/2022				
ENG M. Hart	4/14/2022	TITLE CERDIP28F3-N195x535 DIE PAD 4.95 x13.5mm			
MFG		SCALE	SIZE	DRAWING NO.	REV
QA		3:1	A	281953	A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 4
REVISED					

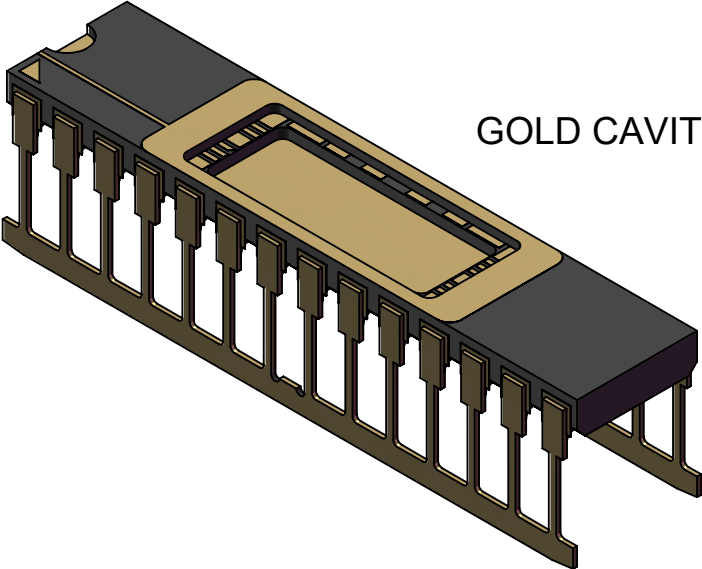
BONDING PADS



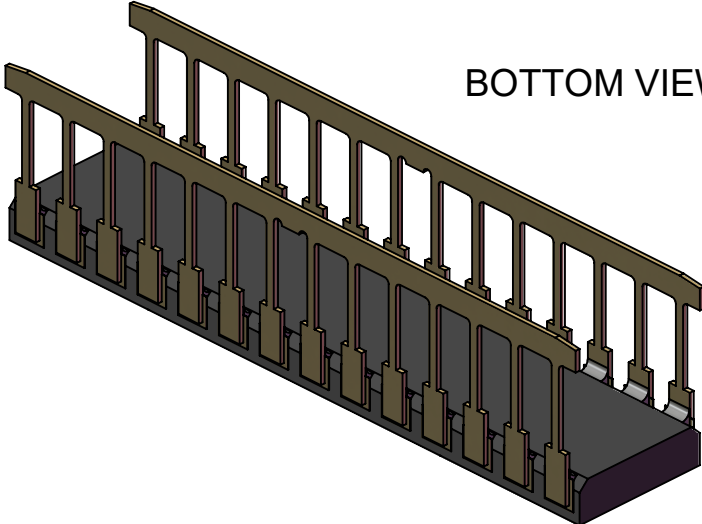
PART NUMBER TABLE		
PART NUMBER	DIE PAD	DWG
CERDIP28F3-N195x535	GOLD	281953

			
TITLE		CERDIP28F3-N195x535 DIE PAD 4.95 x13.5mm	
SCALE	SIZE	DRAWING NO.	REV
10:1	A	281953	A
DO NOT SCALE DRAWING			SHEET 2 OF 4

MODELS



GOLD CAVITY



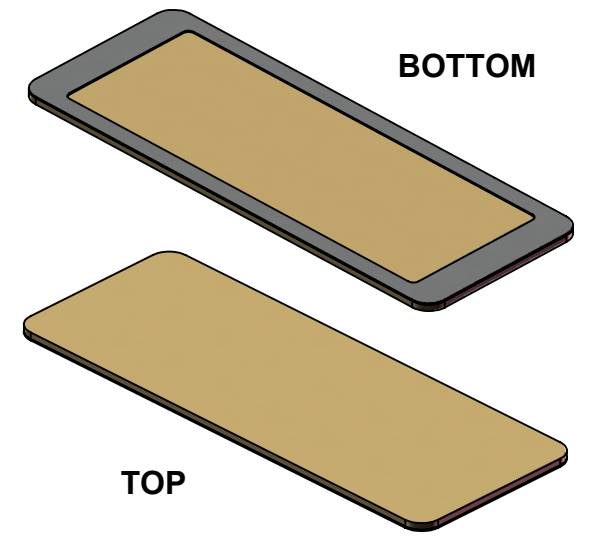
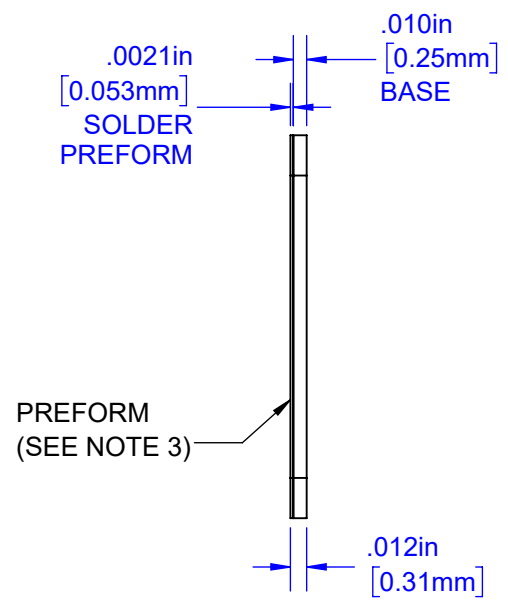
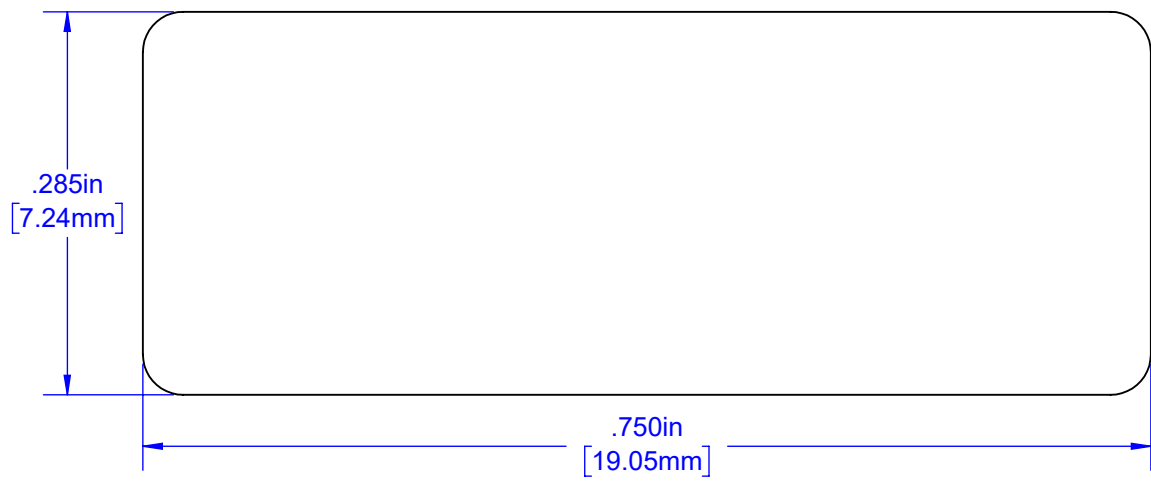
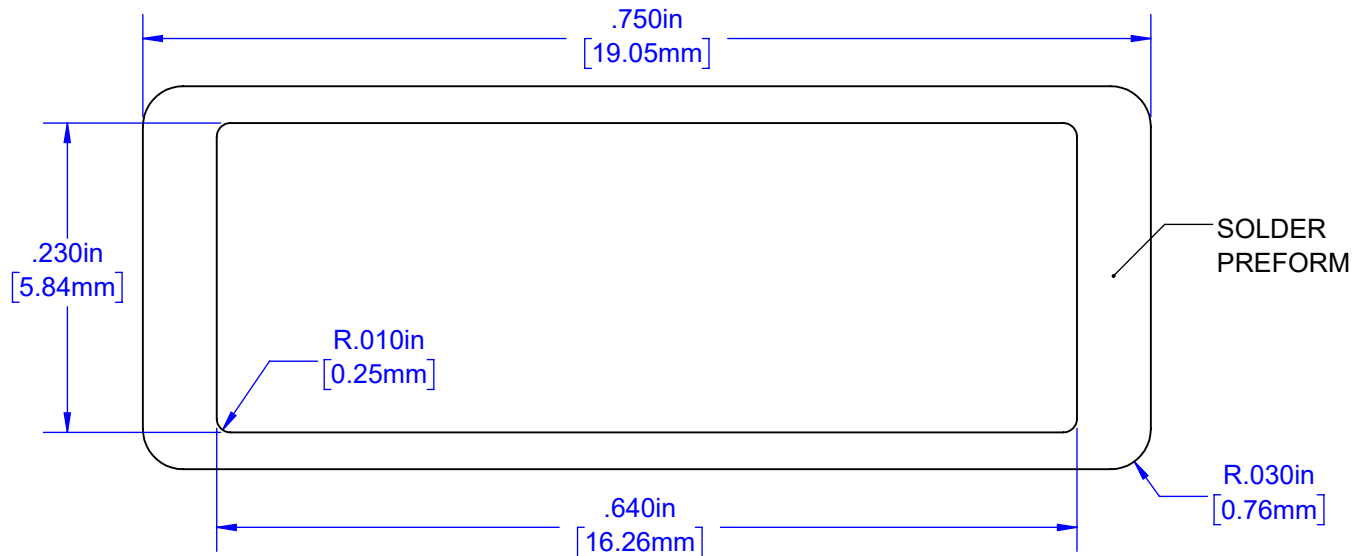
BOTTOM VIEW

PART NUMBER TABLE		
PART NUMBER	DIE PAD	DWG
CERDIP28F3-N195x535	GOLD	281953

TopLine®			
TITLE		CERDIP28F3-N195x535 DIE PAD 4.95 x13.5mm	
SCALE	SIZE	DRAWING NO.	REV
3:1	A	281953	A
DO NOT SCALE DRAWING			SHEET 3 OF 4

COMBO LID OPTIONAL

BOTTOM



MODEL

NOTES:

1. BASE MATERIAL: KOVAR or ALLOY 42.
2. PLATING: Ni 50~350 MICRO-INCH PER SIDE.
Au 25 MICRO-INCH MIN PER SIDE.
3. SOLDER PREFORM: Au 80% ± 1.0 Sn 20%.
4. FLATNESS: 1.0 MIL (25µm) MAXIMUM PER 0.5-inch (12.7mm).

REF: W519H

TopLine®			
TITLE		CL-285x750-A COMBO LID	
SCALE	SIZE	DRAWING NO.	REV
7:1	A	167501	A
DO NOT SCALE DRAWING			SHEET 4 OF 4